



(51) International Patent Classification:

B24D 11/02 (2006.01) **B24D 11/00** (2006.01)
B24D 7/06 (2006.01) **B24B 37/04** (2006.01)
B24D 18/00 (2006.01)

(21) International Application Number:

PCT/US2010/062205

(22) International Filing Date:

28 December 2010 (28.12.2010)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

61/291,182 30 December 2009 (30.12.2009) US

(71) Applicant (for all designated States except US): **3M INNOVATIVE PROPERTIES COMPANY**; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **JOSEPH, William D.**; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US). **GOERS, Brian D.**; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).

(74) Agents: **KULPRATHIPANJA, Ann** et al.; 3M Center, Office of Intellectual Property Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM,

AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))
- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))

Published:

- without international search report and to be republished upon receipt of that report (Rule 48.2(g))

(54) Title: ORGANIC PARTICULATE LOADED POLISHING PADS AND METHOD OF MAKING AND USING THE SAME

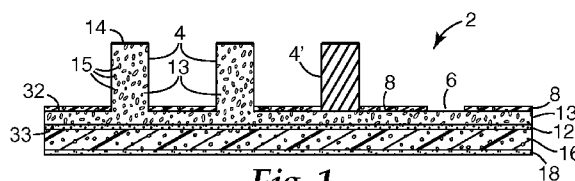


Fig. 1

(57) Abstract: Polishing pads including organic particulates in a continuous polymer phase, and methods of making and using such pads in a polishing process. In one exemplary embodiment, the polishing pads include a multiplicity of polishing elements integrally formed in a sheet. In another exemplary embodiment, the polishing elements are bonded to a support layer, for example by thermal bonding. In certain embodiments, the polishing pad may additionally include a compliant layer affixed to the support layer, and optionally, a polishing composition distribution layer.